

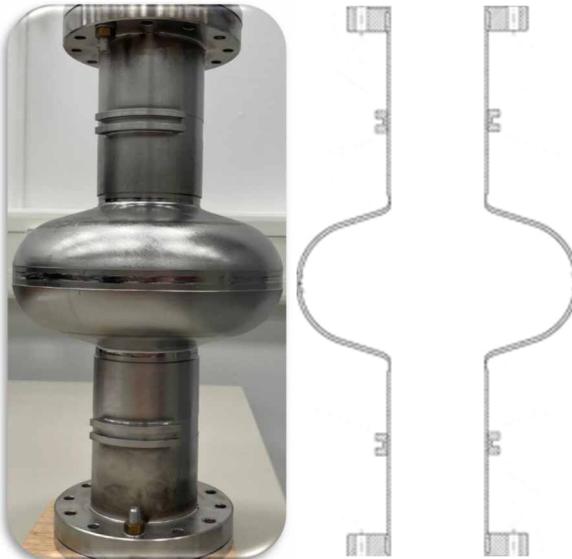


Successful SIS multilayer activities on cavities and samples using ALD

Isabel González Díaz-Palacio on behalf on SRF R&D team
igonza@physnet.uni-hamburg.de

Pushing SRF cavities performance beyond Nb limits

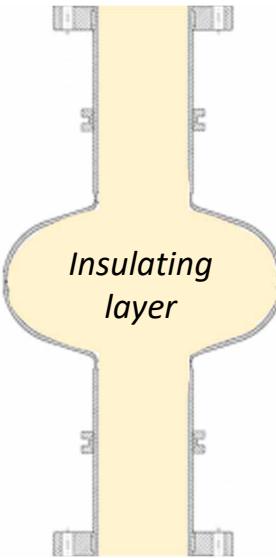
Depositing thin-film superconductor-insulator-superconductor (SIS) multilayers on the inner surface of a SRF cavity



Single-cell 1.3 GHz SRF cavity

Pushing SRF cavities performance beyond Nb limits

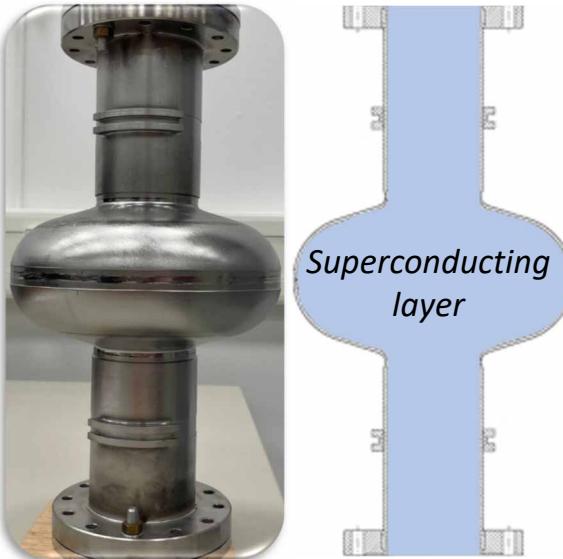
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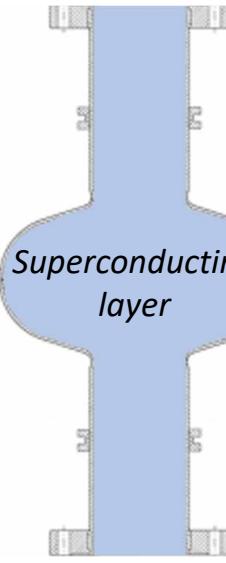
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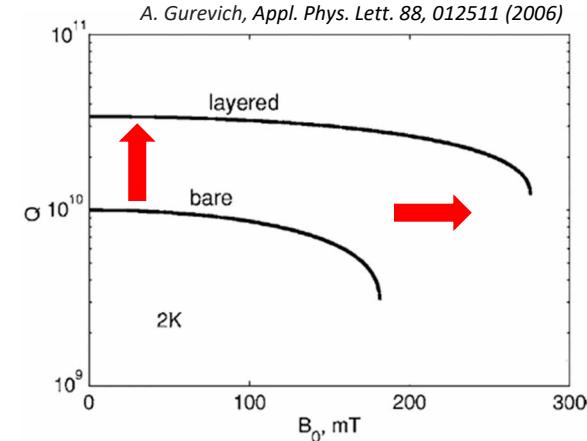
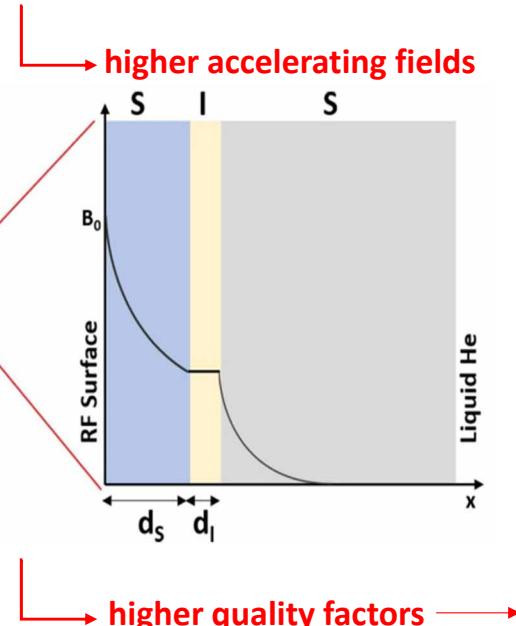
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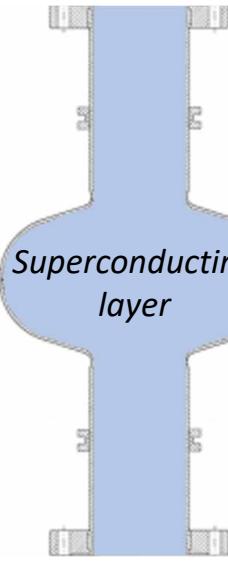


Material candidates for SIS

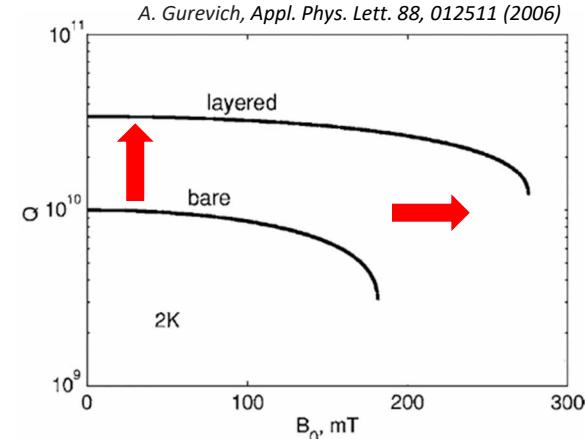
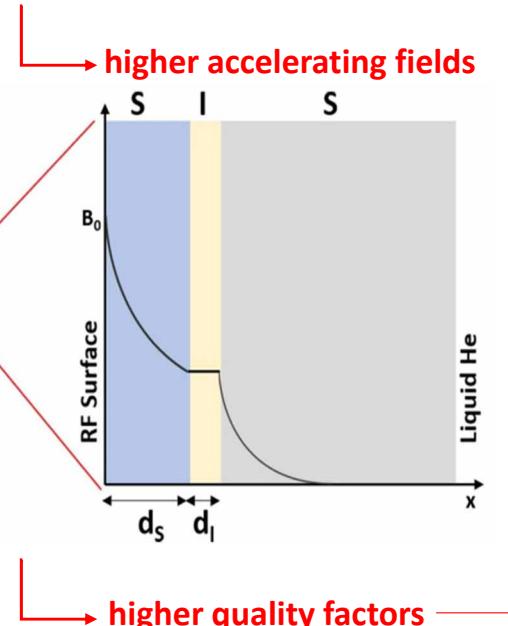
- S: NbN, NbTiN, Nb_3Sn , V_3Si , MoN, ...
- I: AlN, Al_2O_3 , Nb_2O_5 , MgO, ...

Pushing SRF cavities performance beyond Nb limits

Depositing thin-film superconductor-insulator-superconductor (SIS) multilayers on the inner surface of a SRF cavity



Single-cell 1.3 GHz SRF cavity



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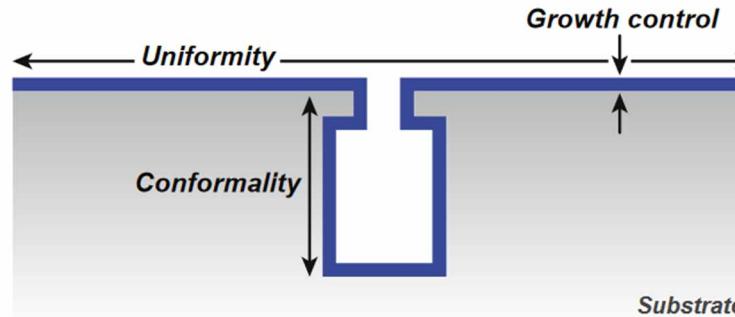
How is the inner surface of the cavity coated?

- Atomic layer deposition (ALD)

Why ALD is an ideal deposition technique for coating SRF cavities

ALD is a chemical vapor phase deposition technique that is distinguished by the key aspects:

- * Surface controlled (gas-solid surface reactions)
- * Self-saturating
- * Sequential



Knoops et al., Handbook of Crystal Growth Vol III, 2nd ed. (2015)

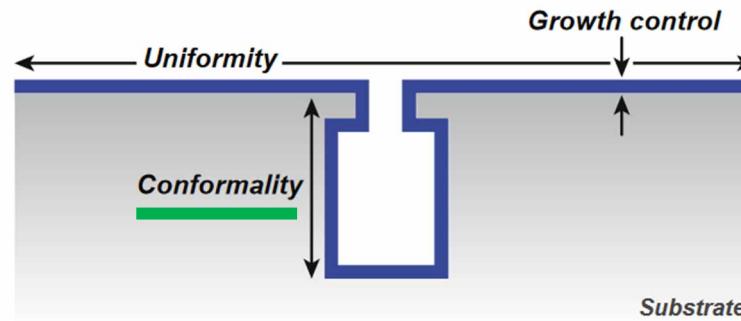
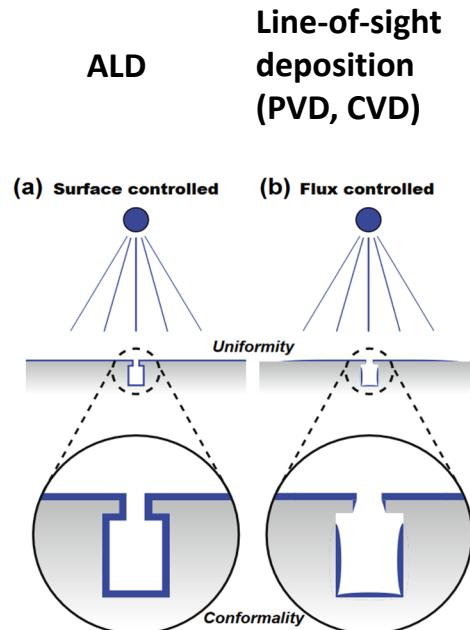
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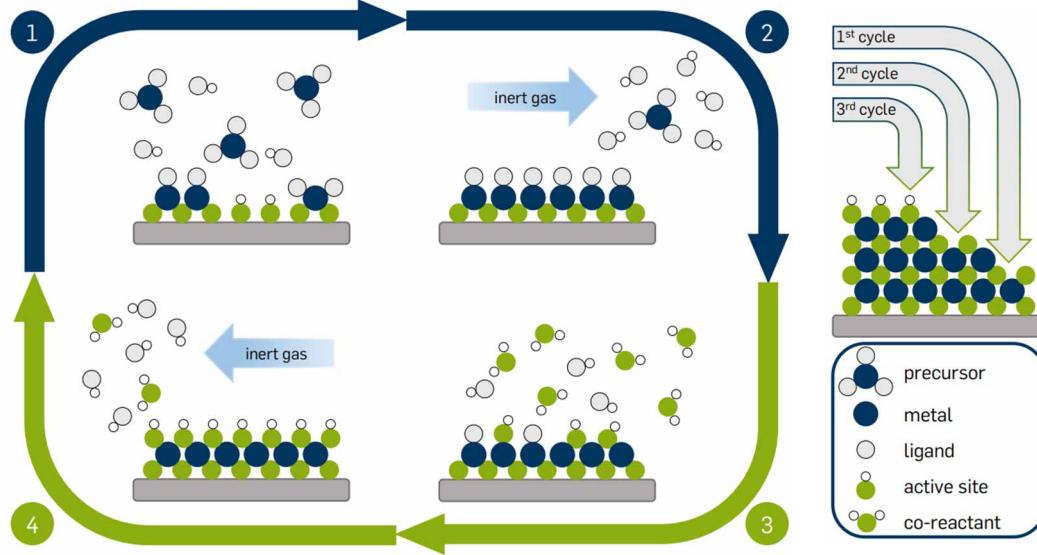
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Knoops et al., Handbook of Crystal Growth Vol III, 2nd ed. (2015)

How does ALD work? Thermal and plasma-enhanced ALD (PEALD)

Thermal ALD

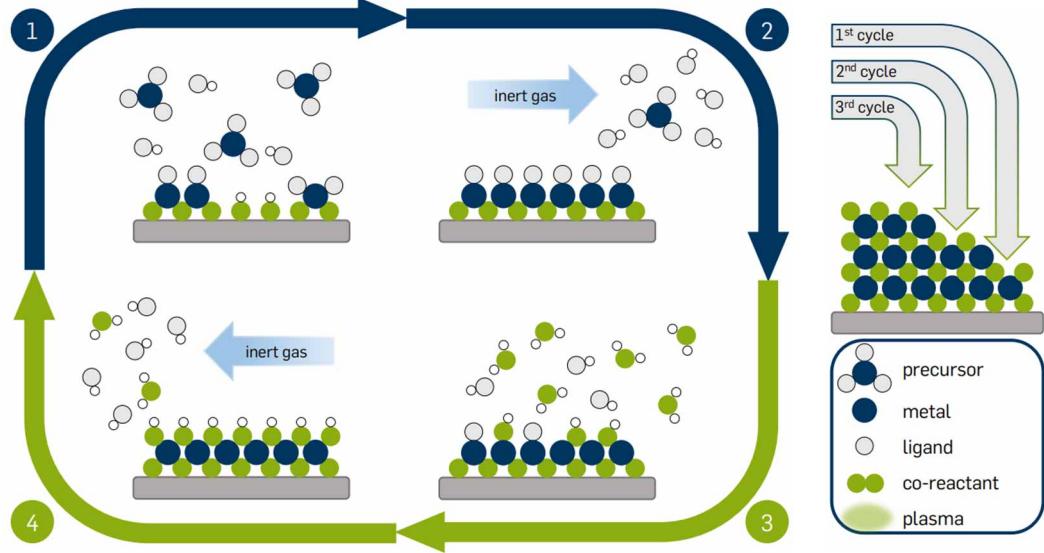


L. Mai, (2020), DOI:10.13154/294-7658.

SRF2023, Isabel González Díaz-Palacio, UHH

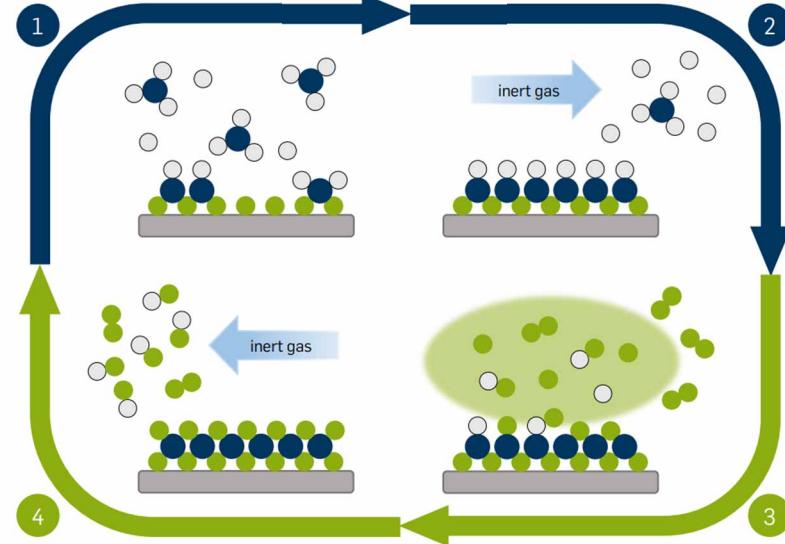
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PEALD



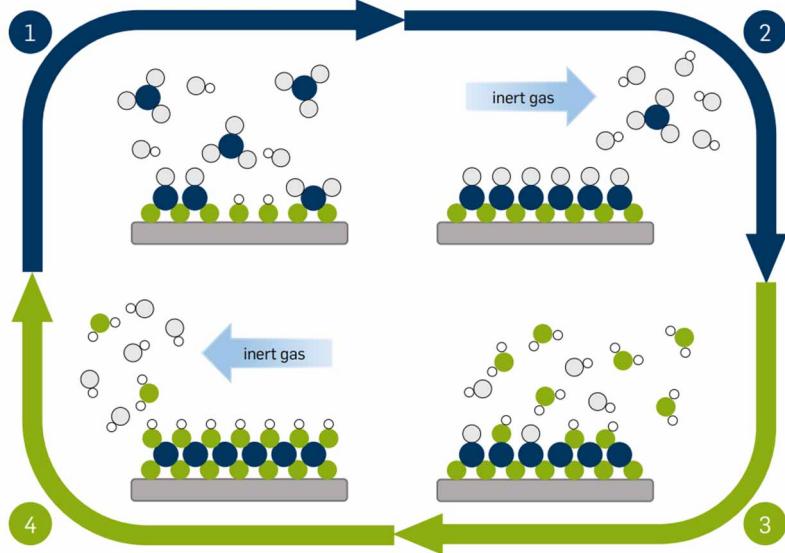
SRF2023, Isabel González Díaz-Palacio, UHH

How does ALD work? Thermal and plasma-enhanced ALD (PEALD)

Material candidates for SIS

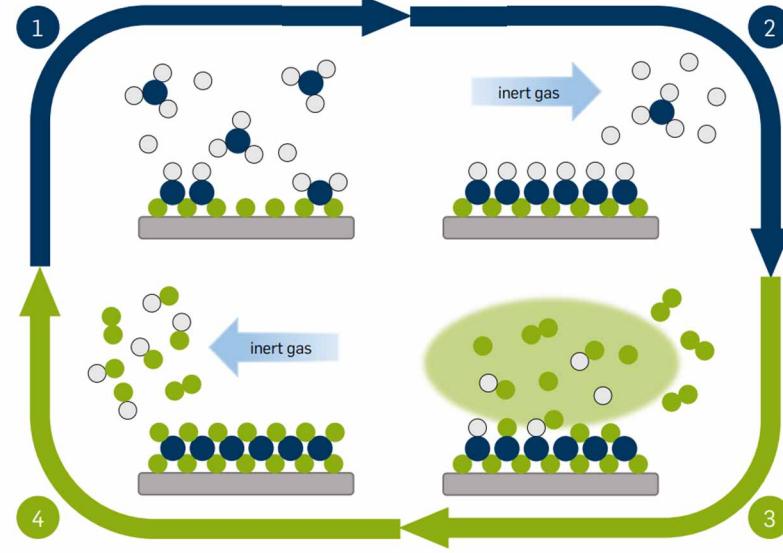
- *S*: NbN, NbTiN
- *I*: AlN, Al₂O₃

Thermal ALD



Deposition choice at UHH: Thermal ALD/PEALD

PEALD



L. Mai, (2020), DOI:10.13154/294-7658.

SRF2023, Isabel González Díaz-Palacio, UHH

SIS multilayers (PE)-ALD investigation at UHH

Thermal ALD: Al_2O_3

*Capability for
coating
single-cell cavities*



PEALD: AlN, NbTiN, NbN

*Capability for
coating
planar samples*



SIS multilayers (PE)-ALD investigation at UHH

Thermal ALD: Al_2O_3

*Capability for
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PEALD: AlN, NbTiN, NbN

*Capability for
coating
planar samples*



Successful Al_2O_3 coating of high-gradient 1.3 GHz cavities by thermal ALD

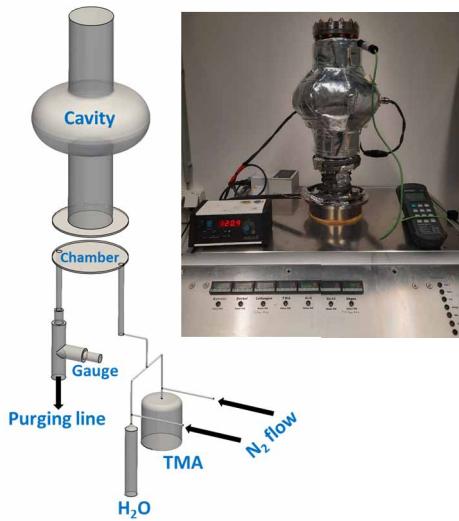
✓ Proof-of-principle experiment

- Process optimization
- Thermal ALD Process Simulation

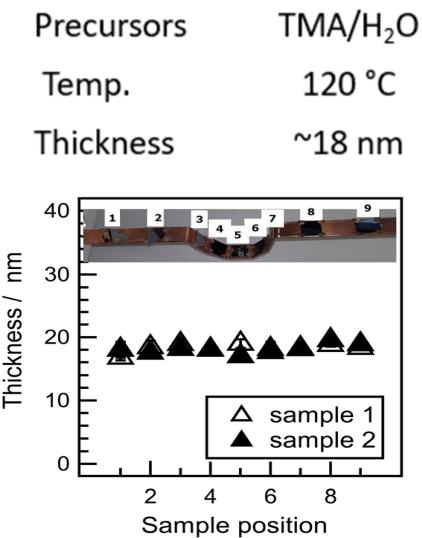
✓ Several single-cell cavities successfully coated

✓ Gradients above 40MV/m without any deterioration in Q-value

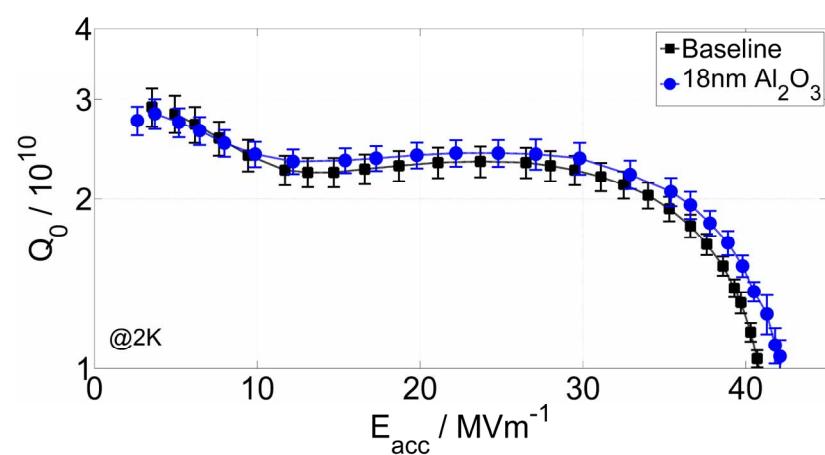
Thermal ALD setup



Process optimization



Cavity performance



Marc Wenskat et al 2023 Supercond. Sci. Technol. **36** 015010 DOI 10.1088/1361-6668/aca83f

For detailed information look at poster ID: **MOPMB016** (Getnet Kacha Deyu)

SIS multilayers (PE)-ALD investigation at UHH

Thermal ALD: Al_2O_3

*Capability for
coating
single-cell cavities*



PEALD: AlN, NbTiN, NbN

*Capability for
coating
planar samples*



How we grow AlN-NbTiN multilayers by PEALD

DEPOSITION PARAMETERS

Temperature: 250 °C

Plasma power: 300 W

Base pressure: 1E-1 mbar



*GEMStar XT-P
from Arradiance*



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GEMStar XT-P
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Precursors: Al, Ti, and Nb

TMA: Trimethylaluminum



H_2/N_2 PLASMA
Plasma reactive species



= AlN

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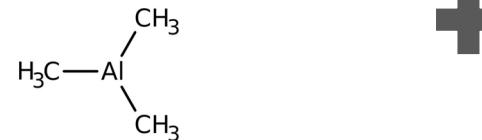


GEMStar XT-P
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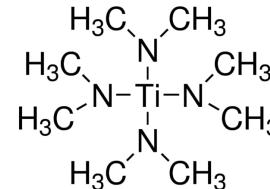


Precursors: Al, Ti, and Nb

TMA: Trimethylaluminum



TDMAT: tetrakis(dimethylamino)titanium(IV)



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= AlN

= TiN

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GEMStar XT-P
from Arradiance



SIS motivation

ALD principle

ALD coating cavities

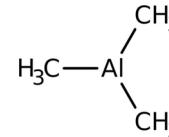
PEALD SIS studies

Outlook

8

Precursors: Al, Ti, and Nb

TMA: Trimethylaluminum

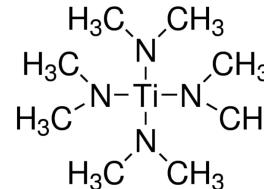


H_2/N_2 PLASMA
Plasma reactive species

= AlN

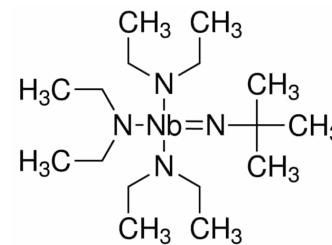


TDMAT: tetrakis(dimethylamino)titanium(IV)



= TiN

TBDTEN: (t-Butylimido)tris(diethylamino)niobium(V)



= NbN

How we grow AlN-NbTiN multilayers by PEALD

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Temperature: 250 °C

Plasma power: 300 W

Base pressure: 1E-1 mbar

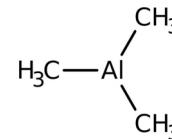


GEMStar XT-P
from Arradiance



Precursors: Al, Ti, and Nb

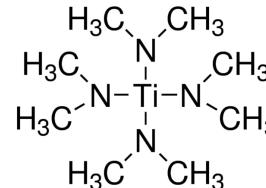
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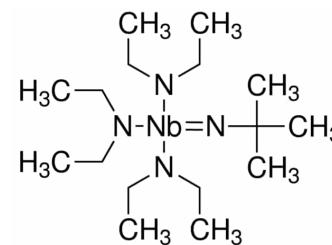
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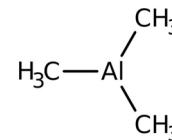


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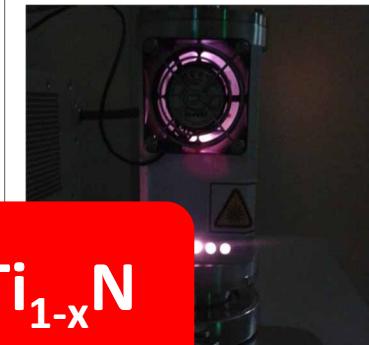
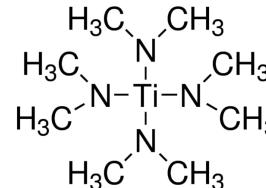
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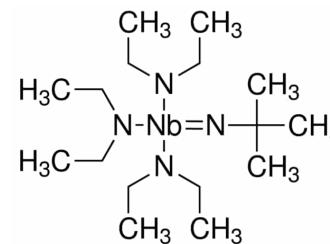
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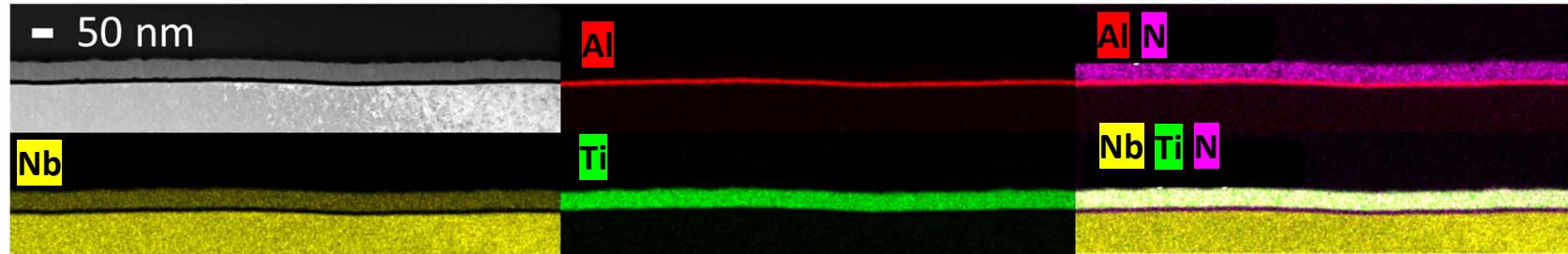


Nb_xTi_{1-x}N



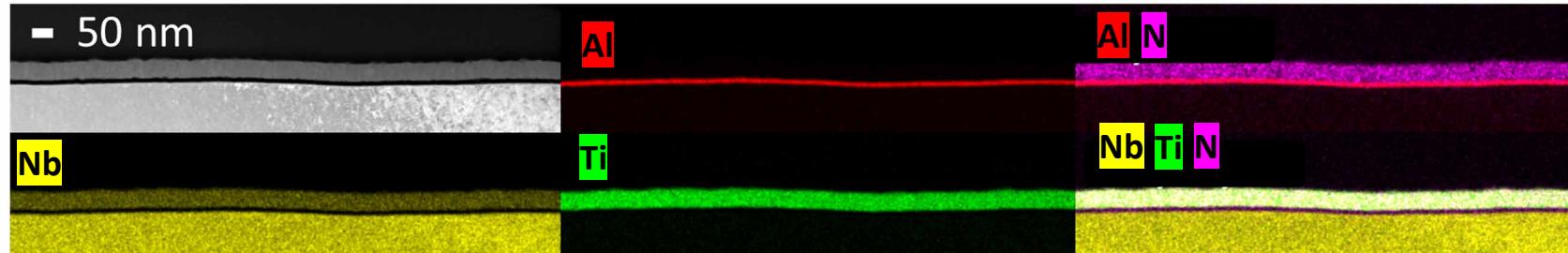
Tailored AlN-NbTiN multilayers deposited by PEALD on Nb and Si substrates

➤ Elemental analysis

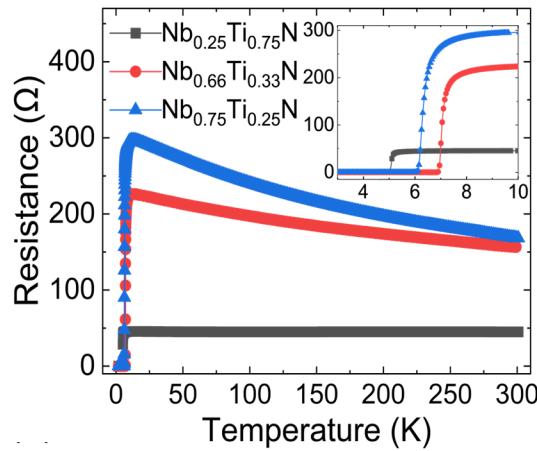


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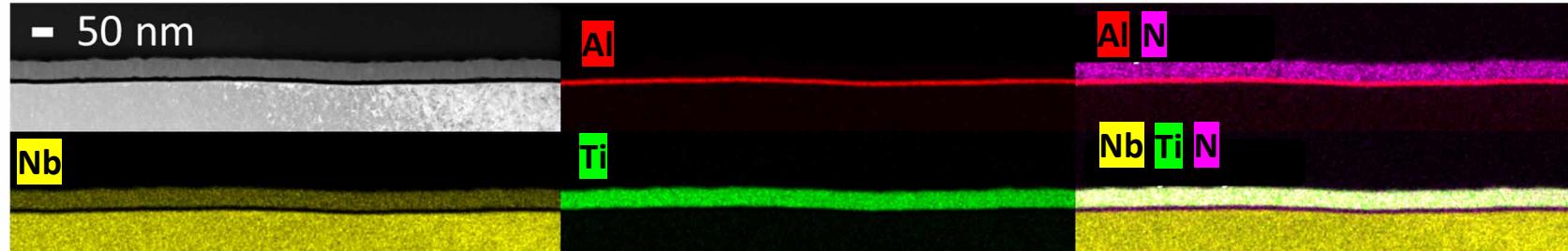


➤ Superconducting $Nb_xTi_{1-x}N$ film composition

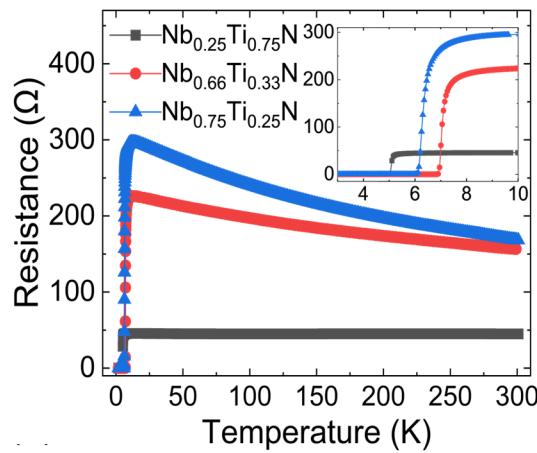


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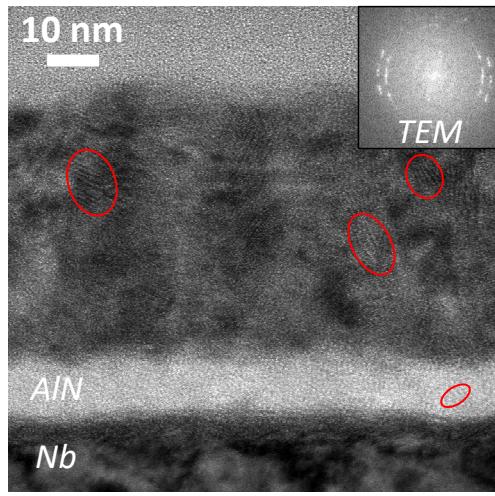
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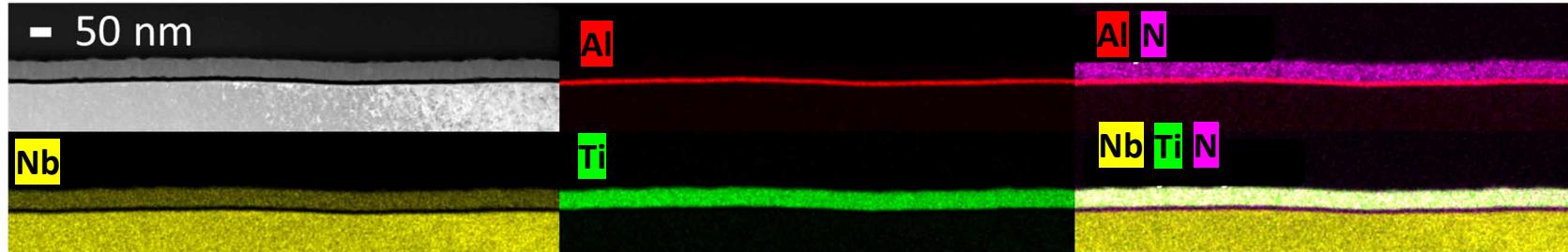


➤ Crystallinity

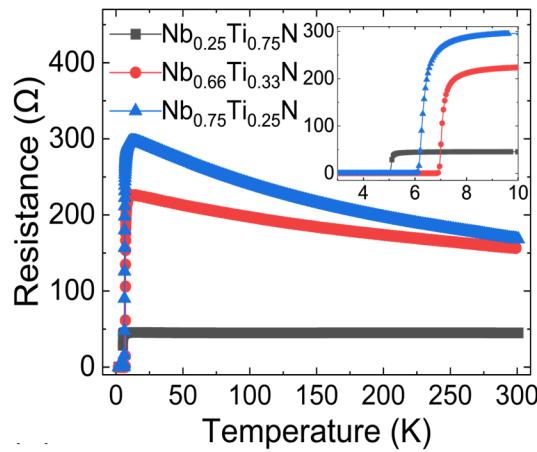


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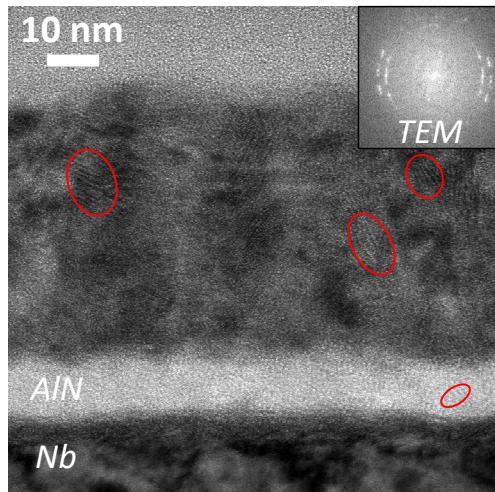
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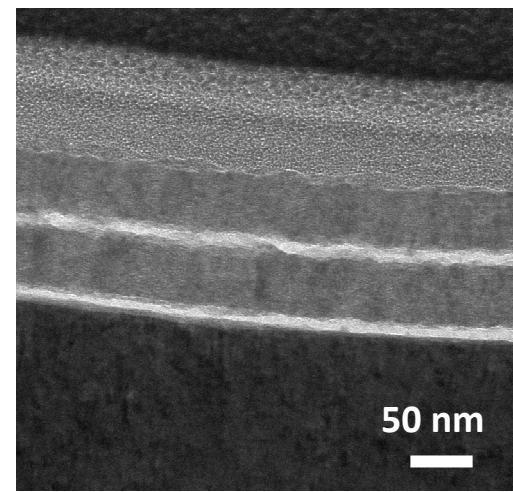
➤ Superconducting $Nb_xTi_{1-x}N$ film composition



➤ Crystallinity



➤ $Nb - (AlN - NbTiN) \times 2$

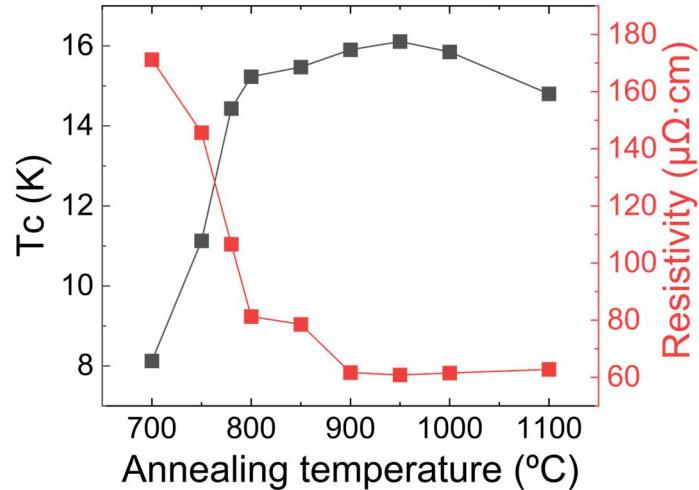


AlN-NbTiN multilayers by PEALD are ready to move on to cavities

- Enhancement superconducting properties annealing

AlN-NbTiN multilayers

Detailed info: I. González Díaz-Palacio et al., Journal of Applied Physics, submitted

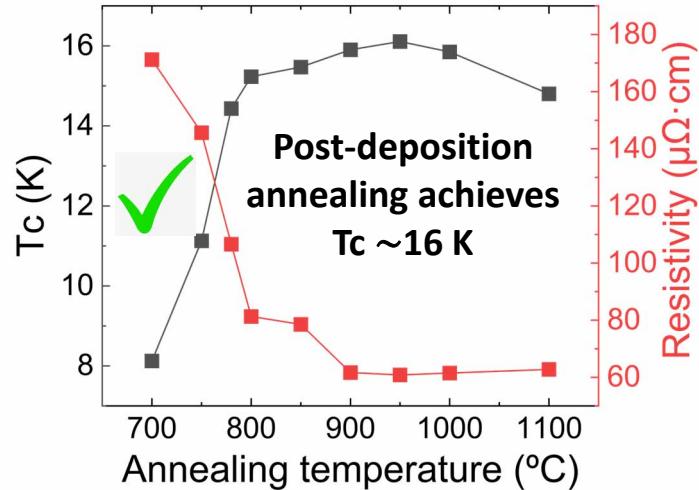


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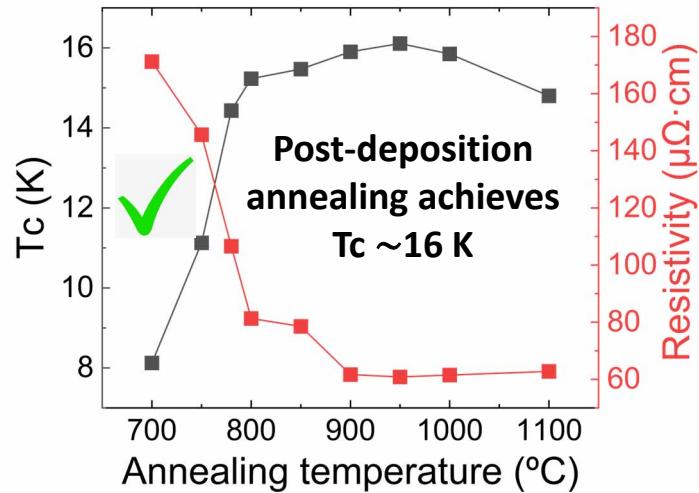
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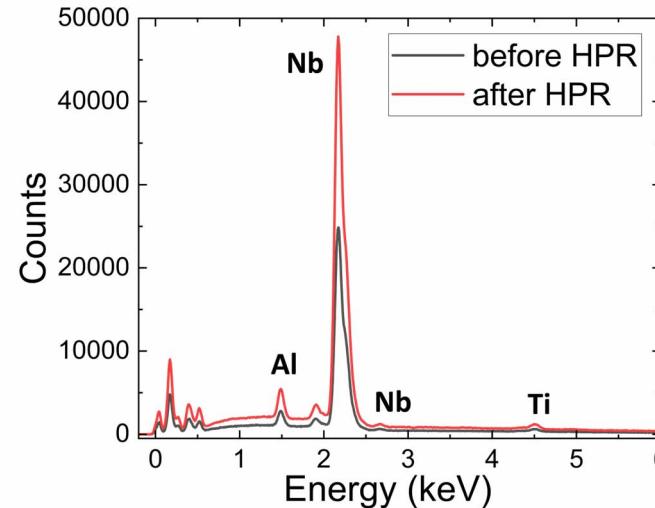
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Detailed info: I. González Díaz-Palacio et al., Journal of Applied Physics, submitted



**Post-deposition annealing achieves
 $T_c \sim 16$ K**

- Success AlN-NbTiN multilayers to cavity preparation techniques: high pressure rinsing (HPR)



DESY facilities
Cleanroom ISO4

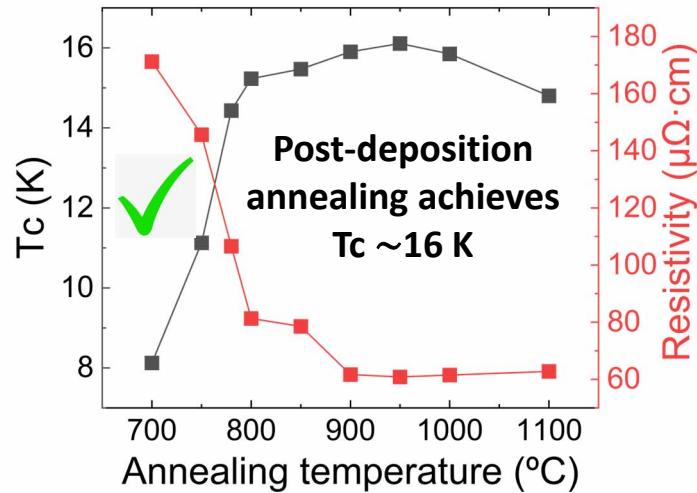


**Layers deposited by (PE)-ALD
survive 7 HPR**

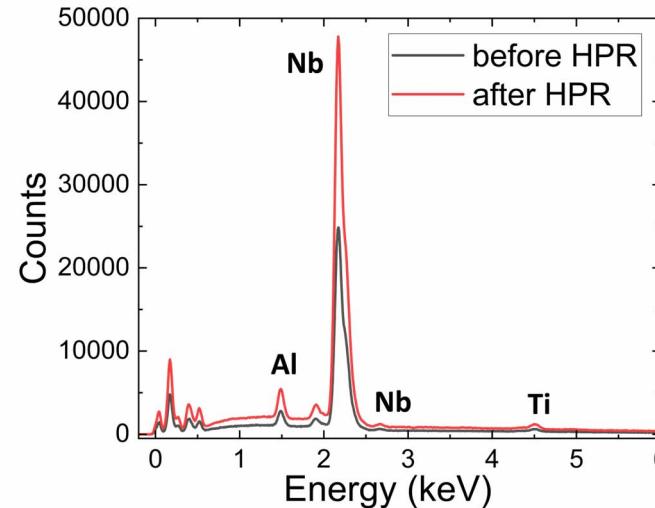
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Detailed info: I. González Díaz-Palacio et al., Journal of Applied Physics, submitted



- Success AlN-NbTiN multilayers to cavity preparation techniques: high pressure rinsing (HPR)



DESY facilities
Cleanroom ISO4

- Field emission from planar films threshold voltage of:



Annealed: 281 MV/m
As-deposited: 95 MV/m



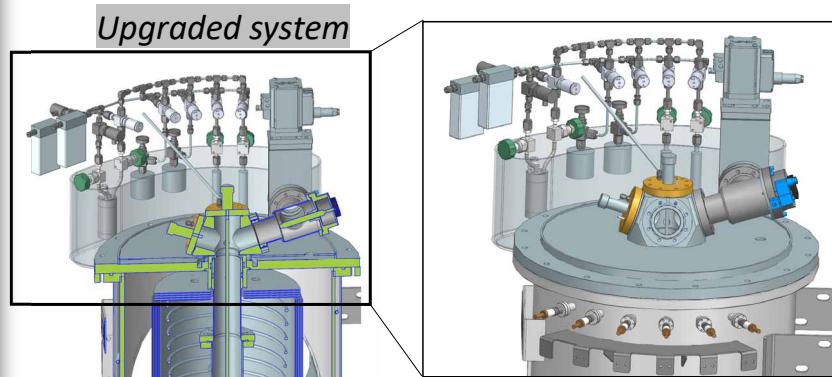
Layers deposited by (PE)-ALD
survive 7 HPR

PEALD AlN-NbTiN cavity coating on the next SRF 2025



For detailed information about the furnace look at poster ID: **WEPWB111** (Marc Wenskat)

EXTEND SINGLE-CELL FURNACE TO PEALD-SINGLE-CELL COATING SYSTEM



Status:

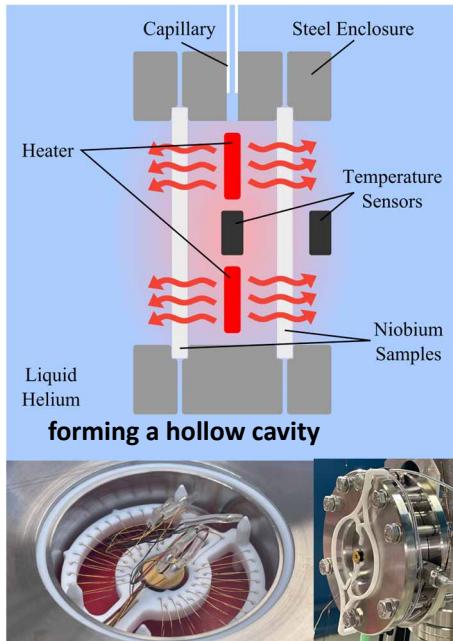
- ✓ Design
- ✓ Fabrication
- Commissioning

High versatility in one system:

- PEALD and thermal ALD
- Capable depositing:
 - NbTiN / NbN
 - AlN
 - Al_2O_3
- In-situ annealing
 - dissolve oxide layers before coating
 - after coating

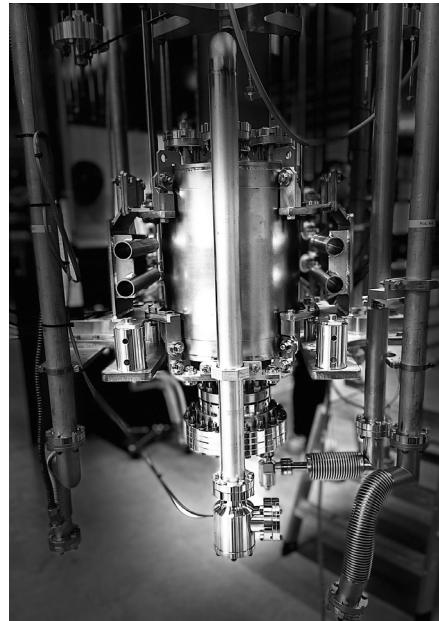
Related activities ongoing

- Thermal conductivity studies at UHH/DESY



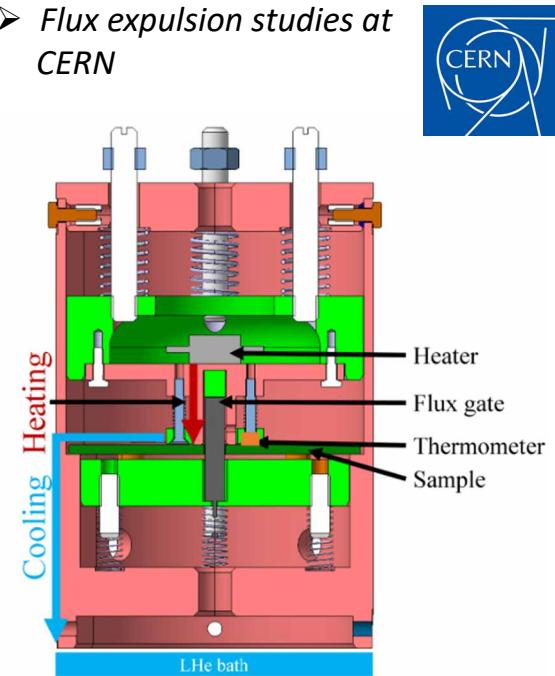
For detailed information look at
poster ID: **MOPMB017** (Cem Saribal)

- Commissioning of the UHH Quadrupole Resonator (QPR) at DESY



For detailed information
talk ID: **THCAA02** (Ricardo Monroy-Villa)

- Flux expulsion studies at CERN



For detailed information look at
poster ID: **MOPMB003** (Daniel A. Turner)

Take home messages

- ✓ Achieve coated cavities by thermal ALD and sustain high accelerating gradients without any performance deterioration
- ✓ SIS multilayers by PEALD and post-deposition annealing have been optimized on planar substrates – move on to cavities
- ✓ SRF2025 SIS coated cavity by PEALD: new setup under development

Thanks to:

SRF R&D group DESY/UHH: Wolfgang Hillert, Hans Weise, Detlef Reschke, Marc Wenskat, Getnet Kacha Deyu, Cornelius Martens, Lea Steder, Rezvan Ghanbari, Lea Preece, Cem Saribal, Nicolay Krupka, Christopher Bate, Ricardo Monroy-Villa, Jonas Wolf, Mateusz Wienczek, and many more. **ALD group UHH (CHyN):** Robert Blick, Robert Zierold, Jun Peng, Carina Hedrich, Stefanie Haugg, Kristian Deneke, Malte Siegmung and more. **Collaborators:** Dirk Lützenkirchen-Hecht (U. Wuppertal), Frederic Braun (U. Wuppertal), Alick Macpherson (CERN), Daniel Turner (CERN), Tobias Junginger (U. Victoria) and more. **Organizing Committee**